

USF NEXUS INITIATIVE 2019 AWARD RECIPIENT

Arash Takshi

Rapid Electrochemical Copper Deposition for Integration of Electronics into Fabrics

This project involves a devised method of electrochemical copper deposition for printing electronic circuit boards and soldering the components on fabrics for the integration of electronics into fabrics. The project aims to address the challenges in fabricating wearable electronics. Assisted by hydrogen evolution during copper electrodeposition, this novel method has demonstrated an incredible printing speed of 0.1 mm/sec. Dr. Takshi's research group from USF will collaborate with scientists at the Intelligent Polymer Research Institute (IPRI) at the University of Wollongong (Australia) for further development of smart textiles.

Partnership:

Javad Foroughi, Ph.D.

University of Wollongong (Wollongong, Australia)



**UNIVERSITY OF
SOUTH FLORIDA**
A PREEMINENT RESEARCH UNIVERSITY